

External_Type	Material_Group	Substances	CAS_Number	Mass	Mass_Percentage_in_Leaf	Massmg
Die	Doped silicon	Silicon (Si)	7440-21-3	0.85182	100.0	1
			Subtotal	0.85182	100	1
Wire	Impurity	Non hazardous		0.00002	0.01	0.00002
	Pure metal	Copper (Cu)	7440-50-8	0.18378	99.99	0.21575
			Subtotal	0.1838	100	0.21577
Lead Frame	Copper alloy	Phosphorous (P)	7723-14-0	0.026	0.05	0.03053
	Copper alloy	Zinc (Zn)	7440-66-6	0.052	0.1	0.06105
	Copper alloy	Iron (Fe)	7439-89-6	1.19608	2.3	1.40415
	Copper alloy	Copper (Cu)	7440-50-8	50.72949	97.55	59.55427
			Subtotal	52.00357	100	61.05
Post-plating	Lead alloy	Tin (Sn)	7440-31-5	0.48554	100.0	0.57
			Subtotal	0.48554	100	0.57
Mould Compound	Polymer	Phenol Formaldehyde resin (generic)	9003-35-4	0.68908	1.5	0.80895
	Polymer	Epichlorohydrin/Diethyleneglycol Epoxy resin (generic)	25928-94-3	4.36417	9.5	5.12335
	Filler	Silica fused	60676-86-0	40.42599	88.0	47.4584
	Carbon Black	Carbon black	1333-86-4	0.45939	1.0	0.5393
			Subtotal	45.93863	100	53.93
Die Attach		Aromatic Polyester Resin	60088-52-0	0.01342	2.5	0.01575
		Paraffin wax	8002-74-2	0.03757	7.0	0.0441
		Epoxy resin system		0.10733	20.0	0.126
		Silver (Ag)	7440-22-4	0.37834	70.5	0.44415
			Subtotal	0.53666	100	0.63
			Total	100.00002	100	117.39577

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